

Filename: BILLOFMATERIALS_bom.xls

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PMP7076_RevB BOM

COUNT	RefDes	Value	Description	Size	Part Number	MFR
1	C1	DNP	Capacitor, multi pattern, SM 1210 to E case + F THole	Multi sizes		Std
1	C2	2.2uF	Capacitor, Ceramic, 50V, X7R, 10%	1210		Std
1	C3	2.2uF	Capacitor, Ceramic, 50V, X7R, 10%	1210		Std
1	C4	0.022uF	Capacitor, Ceramic, 25V, X7R, 10%	0603		Std
1	C6	0.1uF	Capacitor, Ceramic, 10V, X7R, 10%	0603		Std
1	C7	2200pF	Capacitor, Ceramic, 50V, X7R, 10%	0603		Std
1	C8	18pF	Capacitor, Ceramic, 25V, X5R, 20%	0603		Std
1	C10	1uF	Capacitor, Ceramic,	0805	STD	STD
1	C11	2.2uF	Capacitor, Ceramic,	0805	STD	STD
1	C12	0.01uF	Capacitor, Ceramic,	0603	STD	STD
2	C5 C100	47uF	Capacitor, Ceramic, 10V, X5R, 20%	1210		Std
1	D1	B240	Diode, Schottky, 40V, 2A	SMB	B240	
3	J1-3	ED555/2DS	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25""		OST
1	L1	27uH	Inductor, SMT, yyA, zzmiliohm		MSS1038-273	Coilcraft
1	R1	340k	Resistor, Chip, 1/16W, 1%	0603		Std
1	R2	22.1k	Resistor, Chip, 1/16W, 1%	0603		Std
1	R3	237k	Resistor, Chip, 1/16W, 1%	0603		Std
1	R4	40.2k	Resistor, Chip, 1/16W, 1%	0603		Std
1	R5	49.9	Resistor, Chip, 1/16W, 1%	0603		Std
1	R6	52.3k	Resistor, Chip, 1/16W, 1%	0603		Std
1	R7	10.0k	Resistor, Chip, 1/16W, 1%	0603		Std
1	R8	0	Resistor, Chip, 1/16W, x%	0603	Std	Std
7	TP1 TP3-4 TP6-9	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch		Keystone
3	TP2 TP5 TP10	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch		Keystone
1	U1	TPS54140DGQ	IC, DC-DC Converter With Eco-Mode, 1.5A, 42V	MSOP-10	TPS54140DGQ	TI
1	U2	TPS73533DRB	IC, 500mA, Low Quiescent Current, Ultra-Low Noise, Hig	SON-8	TPS735xxDRB	TI

- Notes:
1. These assemblies are ESD sensitive, ESD precautions shall be observed.
 2. These assemblies must be clean and free from flux and all contaminants.
Use of no clean flux is not acceptable.
 3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
 4. Ref designators marked with an asterisk ('**') cannot be substituted.
All other components can be substituted with equivalent MFG's components.

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